

Contents

Preface

xiii

Part I—Fabrication

Chapter 1: Introduction	3
1.1 What are MEMS?	3
1.2 Why MEMS?	4
1.2.1. Low cost, redundancy and disposability	4
1.2.2. Favorable scalings	5
1.3 How are MEMS made?	8
1.4 Roadmap and perspective	12
Essay: The Role of Surface to Volume Atoms as Magnetic Devices Miniaturize	12
 Chapter 2: The substrate and adding material to it	 17
2.1 Introduction	17
2.2 The silicon substrate	17
2.2.1 Silicon growth	17
2.2.2 It's a crystal	19
2.2.3 Miller indices	20
2.2.4 It's a semiconductor	24
2.3 Additive technique: Oxidation	35
2.3.1 Growing an oxide layer	35
2.3.2 Oxidation kinetics	37
2.4 Additive technique: Physical vapor deposition	40
2.4.1 Vacuum fundamentals	41
2.4.2 Thermal evaporation	46
2.4.3 Sputtering	51
2.5 Other additive techniques	57

2.5.1	Chemical vapor deposition	57
2.5.2	Electrodeposition	58
2.5.3	Spin casting	58
2.5.4	Wafer bonding	58
	Essay: Silicon Ingot Manufacturing	59
 Chapter 3: Creating and transferring patterns— Photolithography		 65
3.1	Introduction	65
3.2	Keeping it clean	66
3.3	Photoresist	69
3.3.1	Positive resist	69
3.3.2	Negative resist	70
3.4	Working with resist	71
3.4.1	Applying photoresist	71
3.4.2	Exposure and pattern transfer	72
3.4.3	Development and post-treatment	77
3.5	Masks	79
3.6	Resolution	81
3.6.1	Resolution in contact and proximity printing	81
3.6.2	Resolution in projection printing	82
3.6.3	Sensitivity and resist profiles	84
3.6.4	Modeling of resist profiles	86
3.6.5	Photolithography resolution enhancement technology	87
3.6.6	Mask alignment	88
3.7	Permanent resists	89
	Essay: Photolithography—Past, Present and Future	90
 Chapter 4: Creating structures—Micromachining		 95
4.1	Introduction	95
4.2	Bulk micromachining processes	96
4.2.1	Wet chemical etching	96
4.2.2	Dry etching	106
4.3	Surface micromachining	108
4.3.1	Surface micromachining processes	109
4.3.2	Problems with surface micromachining	111
4.3.3	Lift-off	112
4.4	Process integration	113
4.4.1	A surface micromachining example	115

4.4.2	Designing a good MEMS process flow	119
4.4.3	Last thoughts	124
	Essay: Introduction to MEMS Packaging	126
Chapter 5: Solid mechanics		131
5.1	Introduction	131
5.2	Fundamentals of solid mechanics	131
5.2.1	Stress	132
5.2.2	Strain	133
5.2.3	Elasticity	135
5.2.4	Special cases	138
5.2.5	Non-isotropic materials	139
5.2.6	Thermal strain	141
5.3	Properties of thin films	142
5.3.1	Adhesion	142
5.3.2	Stress in thin films	142
5.3.3	Peel forces	149
Part II—Applications		
Chapter 6: Thinking about modeling		157
6.1	What is modeling?	157
6.2	Units	158
6.3	The input-output concept	159
6.4	Physical variables and notation	162
6.5	Preface to the modeling chapters	163
Chapter 7: MEMS transducers—An overview of how they work		167
7.1	What is a transducer?	167
7.2	Distinguishing between sensors and actuators	168
7.3	Response characteristics of transducers	171
7.3.1	Static response characteristics	172
7.3.2	Dynamic performance characteristics	173
7.4	MEMS sensors: principles of operation	178

7.4.1	Resistive sensing	178
7.4.2	Capacitive sensing	181
7.4.3	Piezoelectric sensing	182
7.4.4	Resonant sensing	184
7.4.5	Thermoelectric sensing	186
7.4.6	Magnetic sensing	189
7.5	MEMS actuators: principles of operation	193
7.5.1	Capacitive actuation	193
7.5.2	Piezoelectric actuation	194
7.5.3	Thermo-mechanical actuation	196
7.5.4	Thermo-electric cooling	201
7.5.5	Magnetic actuation	202
7.6	Signal conditioning	204
7.7	A quick look at two applications	206
7.7.1	RF applications	207
7.7.2	Optical applications	207
Chapter 8: Piezoresistive transducers		211
8.1	Introduction	211
8.2	Modeling piezoresistive transducers	212
8.2.1	Bridge analysis	213
8.2.2	Relating electrical resistance to mechanical strain	215
8.3	Device case study: Piezoresistive pressure sensor	221
Chapter 9: Capacitive transducers		231
9.1	Introduction	231
9.2	Capacitor fundamentals	232
9.2.1.	Fixed-capacitance capacitor	232
9.2.2.	Variable-capacitance capacitor	234
9.2.3.	An overview of capacitive sensors and actuators	236
9.3	Modeling a capacitive sensor	239
9.3.1.	Capacitive half-bridge	239
9.3.2.	Conditioning the signal from the half-bridge	243
9.3.3.	Mechanical subsystem	246
9.4	Device case study: Capacitive accelerometer	250

Chapter 10: Piezoelectric transducers	255
10.1 Introduction	255
10.2 Modeling piezoelectric materials	256
10.3 Mechanical modeling of beams and plates	261
10.3.1 Distributed parameter modeling	261
10.3.2 Statics	262
10.3.3 Bending in beams	268
10.3.4 Bending in plates	274
10.4 Case study: Cantilever piezoelectric actuator	276
 Chapter 11: Thermal transducers	 283
11.1 Introduction	283
11.2 Basic heat transfer	284
11.2.1 Conduction	286
11.2.2 Convection	288
11.2.3 Radiation	289
11.3 Case study: Hot-arm actuator	294
11.3.1 Lumped element model	295
11.3.2 Distributed parameter model	300
11.3.3 FEA model	306
Essay: Effect of Scale on Thermal Properties	310
 Chapter 12: Introduction to microfluidics	 317
12.1 Introduction	317
12.2 Basics of fluid mechanics	319
12.2.1 Viscosity and flow regimes	320
12.2.2 Entrance lengths	324
12.3 Basic equations of fluid mechanics	325
12.3.1 Conservation of mass	325
12.3.2 Conservation of linear momentum	326
12.3.3 Conservation equations at a point: Continuity and Navier-Stokes equations	329
12.4 Some solutions to the Navier-Stokes equations	337
12.4.1 Couette flow	337
12.4.2 Poiseuille flow	339
12.5 Electro-osmotic flow	339
12.5.1 Electrostatics	340

12.5.2	Ionic double layers	346
12.5.3	Navier-Stokes with a constant electric field	355
12.6	Electrophoretic separation	357
Essay: Detection Schemes Employed in Microfluidic Devices for Chemical Analysis		362

Part III—Microfabrication laboratories

Chapter 13: Microfabrication laboratories		371
13.1	Hot-arm actuator as a hands-on case study	371
13.2	Overview of fabrication of hot-arm actuators	372
13.3	Cleanroom safety and etiquette	375
13.4	Experiments	377
	Experiment 1: Wet oxidation of a silicon wafer	377
	Experiment 2: Photolithography of sacrificial layer	384
	Experiment 3: Depositing metal contacts with evaporation	388
	Experiment 4: Wet chemical etching of aluminum	392
	Experiment 5: Plasma ash release	395
	Experiment 6: Characterization of hot-arm actuators	397
Appendix A: Notation		405
Appendix B: Periodic table of the elements		411
Appendix C: The complimentary error function		413
Appendix D: Color chart for thermally grown silicon dioxide		415
Glossary		417
Subject Index		439